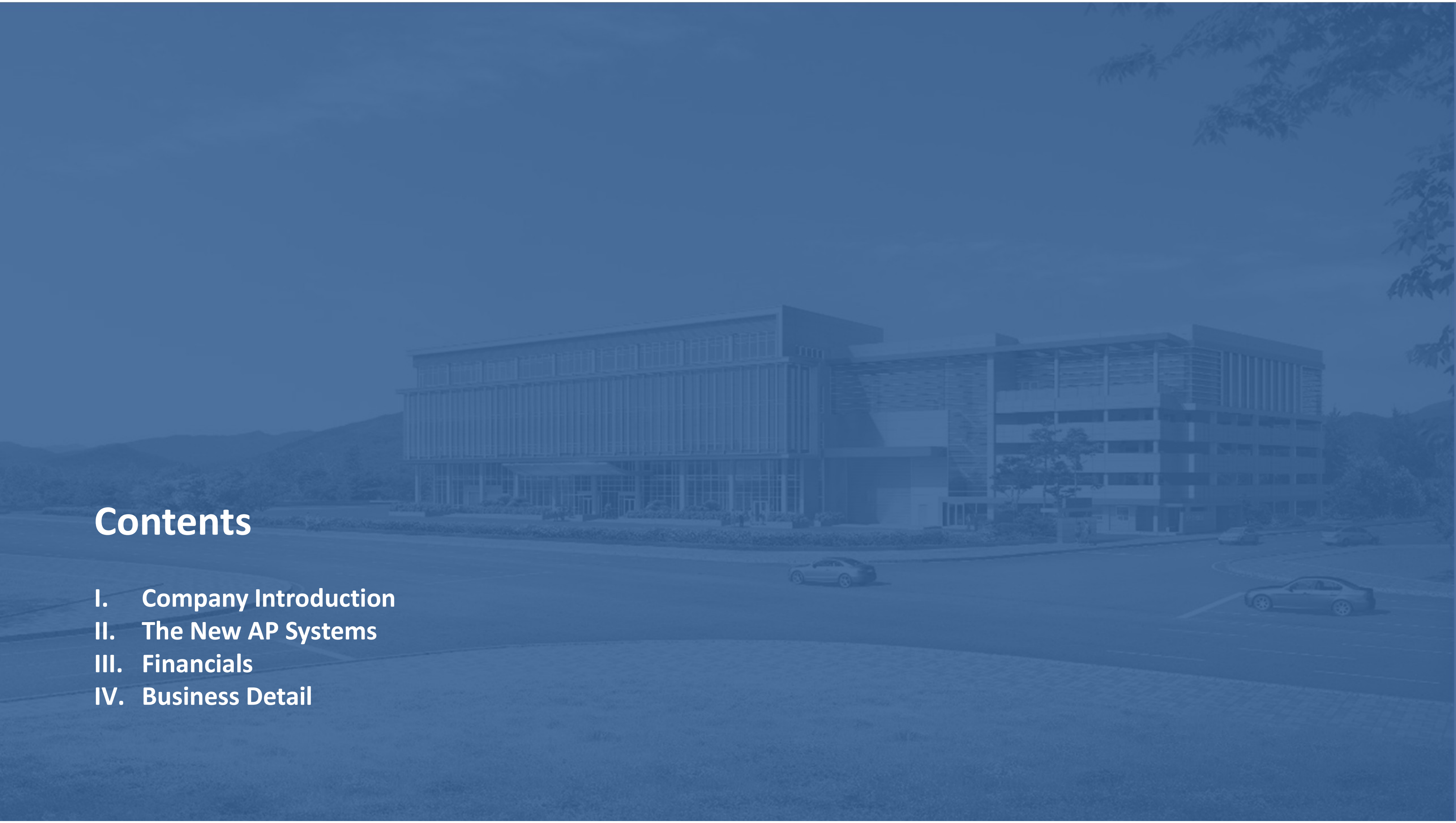
AP Systems
Investor Relations 2025

CREATING VALUE THROUGH TECHNOLOGIES



Contents

I. Company Introduction

- Company Overview
- Growth History
- Global Network and Facilities
- Major Customers

Company Overview

AP Systems

Corporate Structure

APS

APS

Founder : Ki Ro Jung

- former researcher of Electronics and Telecommunication Research Institute
- owns 32.3% shares of APS

KOSDAQ Listed Company

25%	8.9%	11%	42%	63%	31%	52%	46%
AP Systems	**NEXTIN**	**DE&T**	**KORNIC Automation**	**ZenithWorld**	**ASTEL**	**KORNIC SEMITECH**	**Bison Medical**
AP Systems Advanced Process Systems Corporation	NEXTIN Solutions	DE&T DE&T Co.,Ltd. Digital Equipment & Total Solution	KORNIC Automation	ZENITH WORLD	ASTEL	KORNIC SEMITECH	BISON
Manufacturing Equipment (DP,SEMI, EV battery, Solar Cell)	Semiconductor Wafer Inspection System	Secondary Battery Equipment	Display . Semiconductor Equipment Control Software	ESC, Coating, Cleaning & Component Process	Digital X- Ray Total Solution	Semiconductor wafer dicing equipment	Skin care medical equipment

KOSDAQ Listed Company

*AP Systems has 10.4% shares of DE&T Co.,Ltd and 9.3% of NEXTIN Inc.

Organization

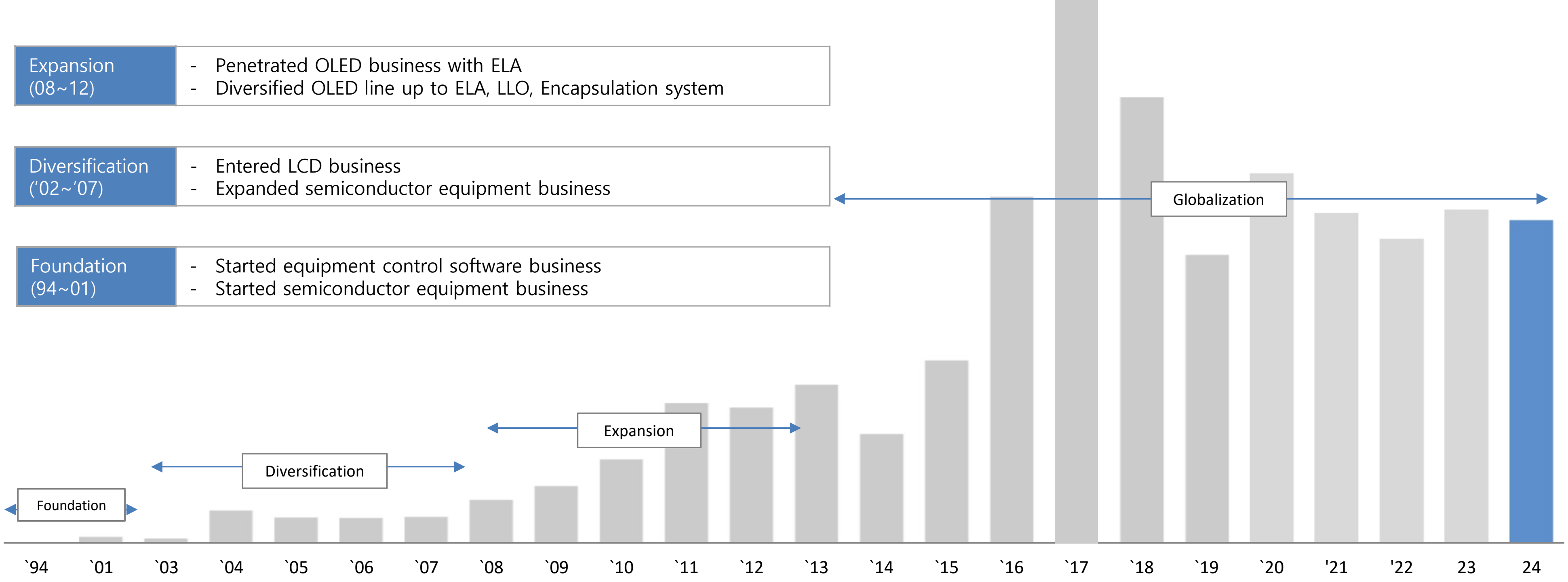
CEO : Yoo Ho Sun

- Established in 1994
- Paid in capital : KRW 7.6 billion
- No. of Employees : 580

Locations: Headquarters: South Korea (Dongtan)
Fab: South Korea (Dongtan, Balan, Cheonan)
Overseas: China (Shanghai), Vietnam (Hanoi),
USA (Georgia)

Growth History

Globalization ('13~present)	- Launched business to oversea market - Dominant presence of ELA(100% M/S excluding LGD) - Started back-end equipment business - Growing presence of Lamination - Penetrated DRAM business with RTP
Expansion (08~12)	- Penetrated OLED business with ELA - Diversified OLED line up to ELA, LLO, Encapsulation system
Diversification ('02~'07)	- Entered LCD business - Expanded semiconductor equipment business
Foundation (94~01)	- Started equipment control software business - Started semiconductor equipment business



* Chart : Annual revenue

Global Network and Facilities

- ● Headquarters
- ● CS Center

APS China

Est. 2013
> Shanghai Office
> CS Centers

APS Vietnam

Est. 2016
> Hanoi Office
> CS Centers

APSYSTEMS AMERICA

Est. 2024
> Georgia Office
> CS Centers

AP Systems

Total Clean Room : 30,000m²

FAB 1 (Dongtan)

Clean Room: **5,200m²**

FAB 2 (Dongtan2)

Clean Room: **4,800m²**

FAB 3 (Cheonan)

Clean Room: **17,200m²**

FAB 4 (Baran)

Clean Room: **2,800m²**

❖Total CAPEX capable of generating sales of $1B

Major Customers

AP Systems

Semiconductor

- SAMSUNG ELECTRONICS
- SK hynix
- cxmt
- JHICC
- SMIC
- CHJS
- YMTC
- Micron
- soitec
- NANYA
- Union SEMICONDUCTOR
- BIWIN.
- SPIL

Display

- SAMSUNG SAMSUNG DISPLAY
- SAMSUNG ELECTRONICS
- JOLED JOLED Inc.
- AUO
- BOE
- 华星光电 CSOT
- EDO
- TIANMA
- TRULY®
- Visionox 维信诺
- ROYOLE

Renewable Energy

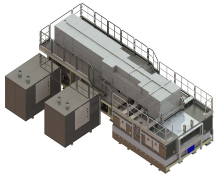
- SK on
- Hanwha Solutions
- Qcells

II. The New AP Systems

- Core Technologies
- Business & Products
- The Next Step

Core Technologies

AP Systems

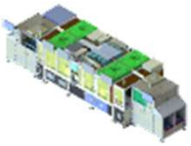

Excimer Laser Annealing(ELA)


NEW

Laser Dicing


NEW

Laser Debonder


Module dispenser


Module Laminating

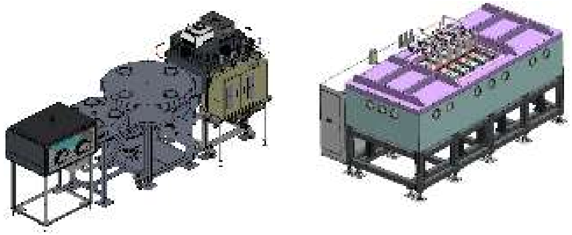

Inkjet Printer

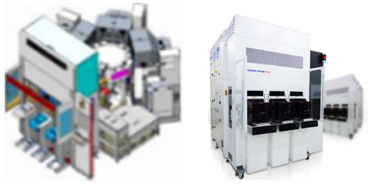
Laser Application Technology

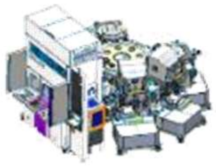
Deposition Technology

Module & Transfer Technology

Thermal Process & Plasma Technology


Atomic Layer Deposition(ALD)


Rapid Thermal Process(RTP)


Sputter

Business & Products

SEMICONDUCTOR

Front-end

Rapid Thermal Process(RTP)

Back-end

Sputter

LASER

Laser Dicing

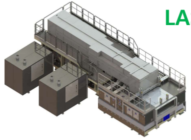
LASER

Laser De-bonder

OLED

Front-end

LASER

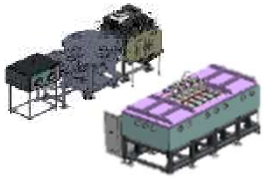


Excimer Laser Annealing(ELA)

LASER

Laser Lift-Off(LLO)

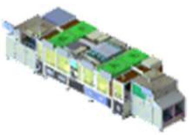
Encapsulation



Atomic Layer Deposition(ALD)

Back-end

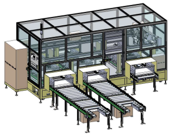
Module Laminating



Module dispenser

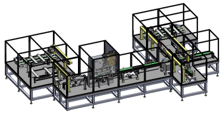
Inkjet Printer

EV BATTERY

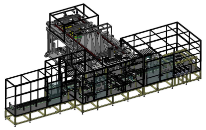


NG Sorter

Tray Washer



Cell Taping



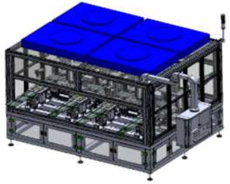
Cell Packing

SOLAR CELL

LASER

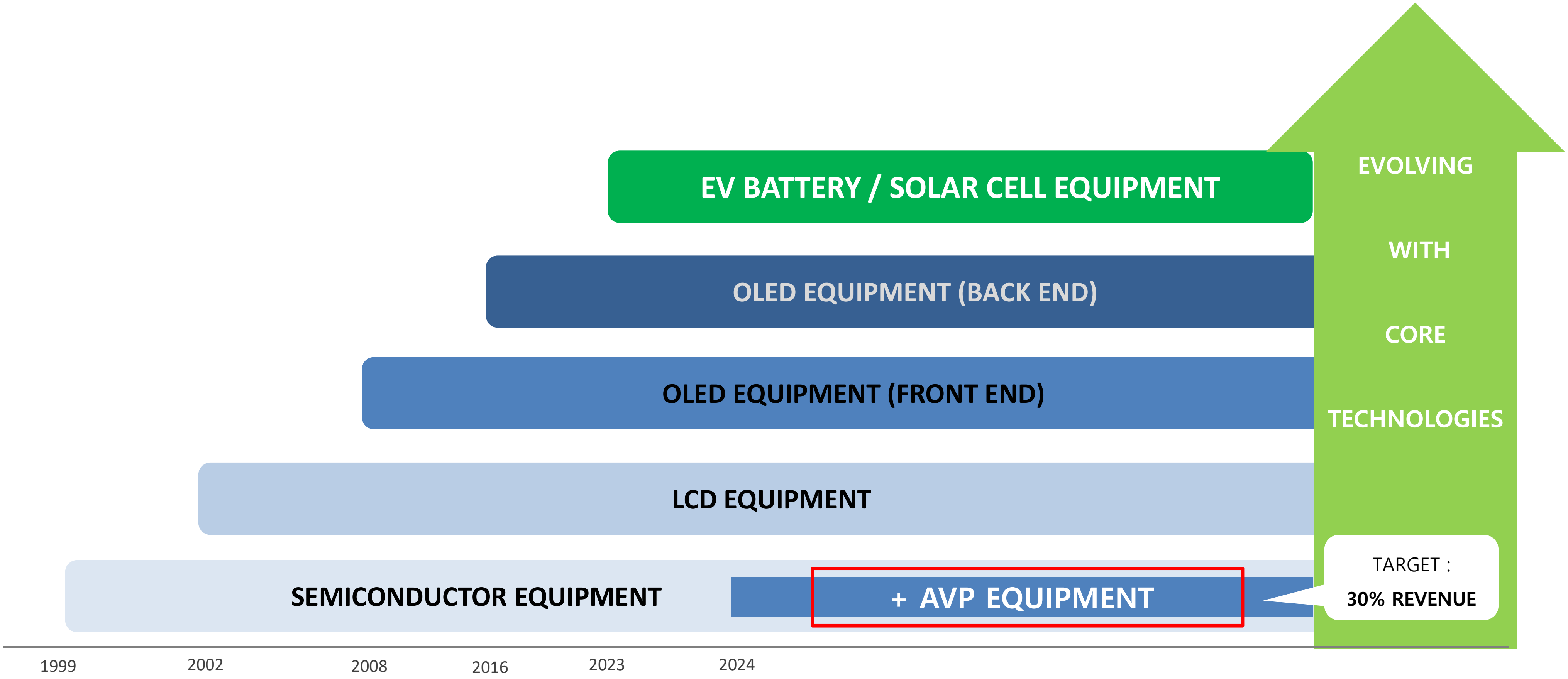
Laser Edge Isolation (LEI)

LASER



Laser Doped Selective Emitters(LDSE)

The Next Step



EV BATTERY / SOLAR CELL EQUIPMENT

OLED EQUIPMENT (BACK END)

OLED EQUIPMENT (FRONT END)

LCD EQUIPMENT

SEMICONDUCTOR EQUIPMENT

+ AVP EQUIPMENT

EVOLVING

WITH

CORE

TECHNOLOGIES

TARGET :

30% REVENUE

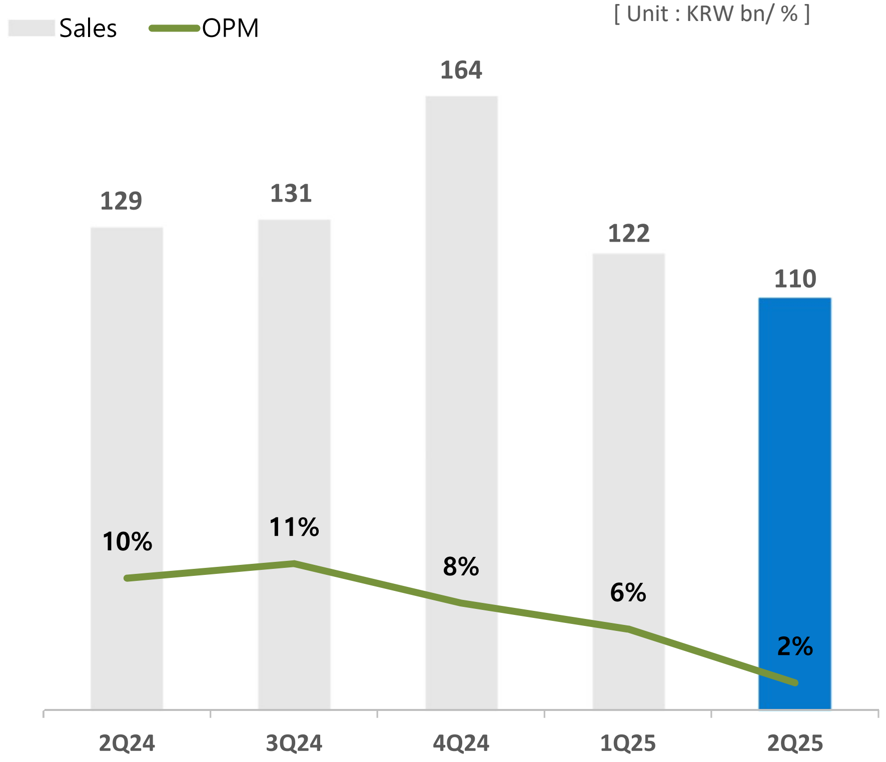
III. Financials

- Business Results : 2Q25
- Consolidated Financial Statements

Business Results : 2Q25

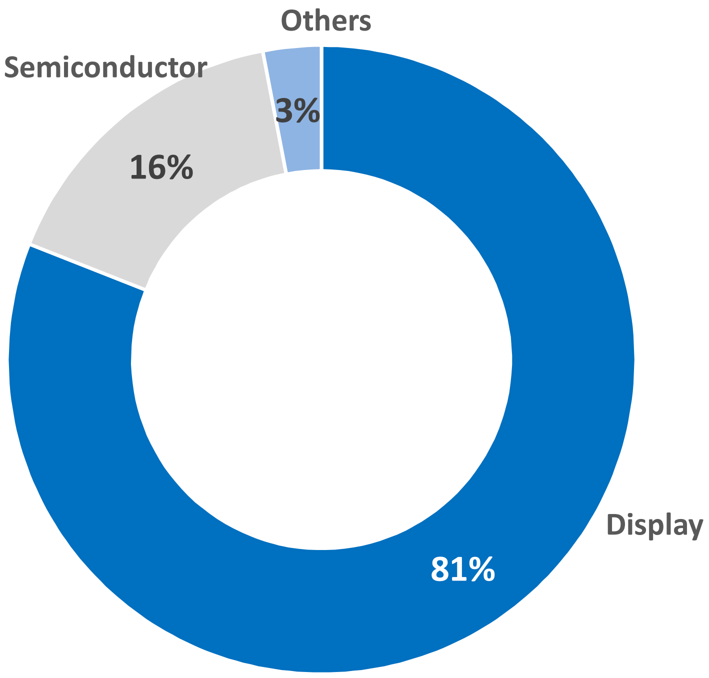
Quarterly Revenue

[Unit : KRW bn/ %]



Revenue Breakdown by Division

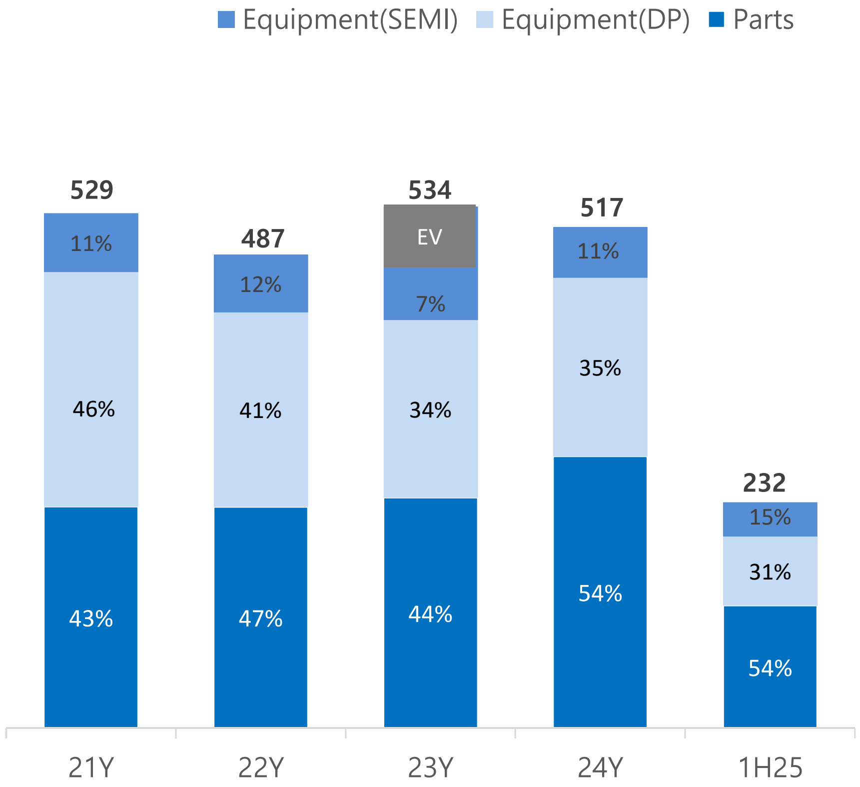
[Jun 2025]



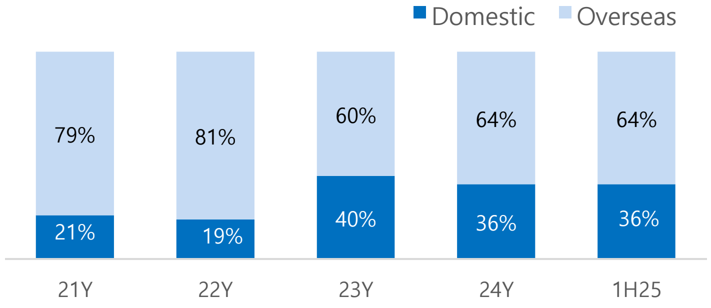
Business Results : 2Q25

Revenue Breakdown by Business Type

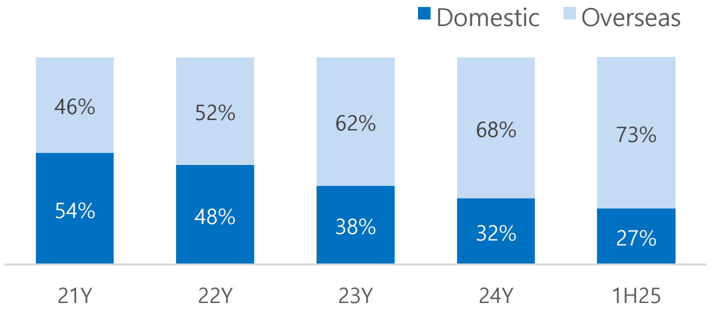
Unit : KRW bn



Equipment Revenue Ratio by Region



Parts Revenue Ratio by Region



Consolidated Financial Statements

AP Systems

Balance Sheet Summary

[Unit : KRW bn]	1H25	2024	2023	2022	2021
Current Assets	328	376	390	396	291
Non-current Assets	212	224	181	152	137
Total Assets	540	600	571	548	429
Current Liabilities	165	197	174	222	136
Non-current Liabilities	46	66	76	55	102
Total Liabilities	210	263	250	277	237
Current Ratio (%)	199%	191%	225%	178%	214%
Debt Ratio (%)	64%	78%	78%	103%	124%
Total Capital	330	337	321	270	192

Income Statement Summary

[Unit : KRW bn]	1H25	2024	2023	2022	2021
Revenue	232	517	534	487	529
Gross Profits	47	100	106	142	114
General Expenses	37	53	46	52	50
Operating Profits	10	47	60	90	64
OP Margin(%)	4.5%	9.1%	11.2%	18.6%	12.1%
Profits before Tax	-0.4	66	76	111	76
Net Profits	1	52	60	82	57

IV. Business Detail

- Display(OLED)
- Semiconductor

Product Line-up for Display(OLED)

Front-end

Back-end

TFT Backplane
- Cleaning
- PI Coating & Curing
- Deposition
- Crystallization
- Photolitho
- Etching
- Baking
- Inspection

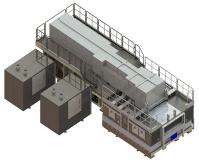
Evaporation
- Cleaning
- Organic Evap.

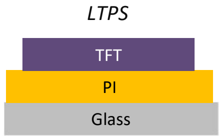
Encapsulation
- Encap.

Module
- Module

Inspection
- Inspection

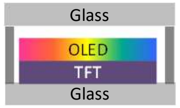
Excimer Laser Annealing





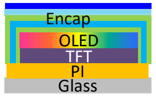
ELA
(Excimer Laser Annealing)

Encapsulation



Glass encap. (Frit)

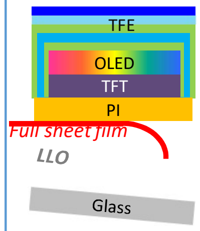
CVD: SiNx + Barrier Film



TFE (hybrid)

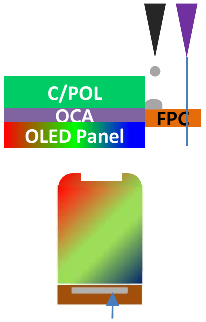
Encap
(Encapsulation)

Laser Lift-Off



LLO
(Laser Lift Off)

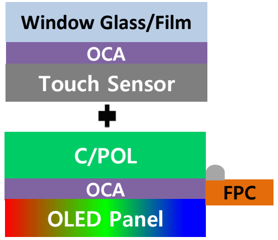
Module Dispensing



Dispensing

MDS
(Module Dispensing System)

Module Laminating



MLS
(Module Laminating System)

Highlights : OLED

NOW

FRONT END

BACK END

ELA, LLO, Encapsulation

Laminating, Dispensing

More Demand

New Investment

&

Equipment / Parts ↑

FUTURE

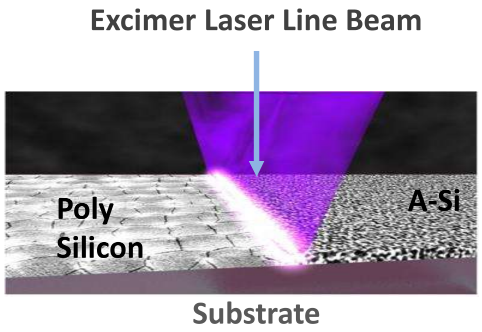
Increase of OLED applications

ELA, LLO, Encapsulation + ALD

Laminating, Dispensing + OCR Inkjet Printer

Signature Equipment

ELA (Excimer Laser Annealing)



**More than 12 years experience in AMOLED*

AP Products

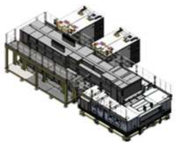
2005 2008 2010 2012 2016 2017


G3.5 Demo (LB380)


G4.5 MP (LB465)


G8 & G5.5 MP (LB750)


G5.5 MP (LB1300)


G6 MP (LB1000)


G6 MP (LB1500)

Evaluation → Enlargement → Leading Advanced Technology

Rigid & WVGA → Rigid & HD → Flexible & FHD / QHD


3.5" 200ppi Haptic AMOLED


4" 233ppi Galaxy S


4.8" 306ppi Galaxy S3


5" 441ppi Galaxy S4


5.5" 534ppi Galaxy Edge 7


5.8" 570ppi Galaxy S20

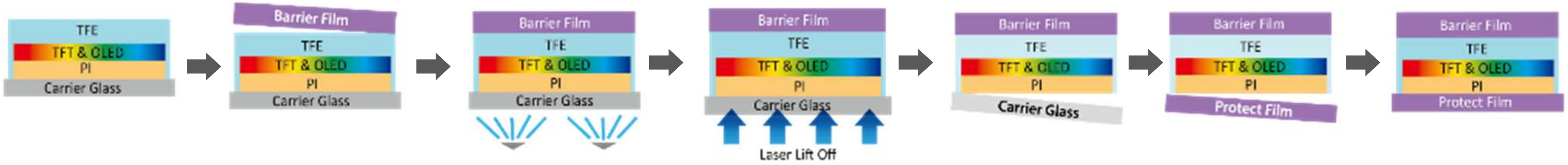
Customer Products

Signature Equipment

AP Systems

LLO (Laser Lift-Off)

Process



TFE → 1st Lami → Cleaning → Release → Remove → 2nd Lami → Product

Structure

Laser(Excimer, DPSS) Irradiation

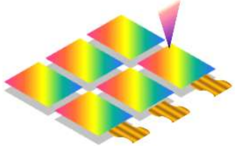
Coating of Plastic Solution → TFT & OLED Process → **LLO Process** → FLC Process → Flexible Display

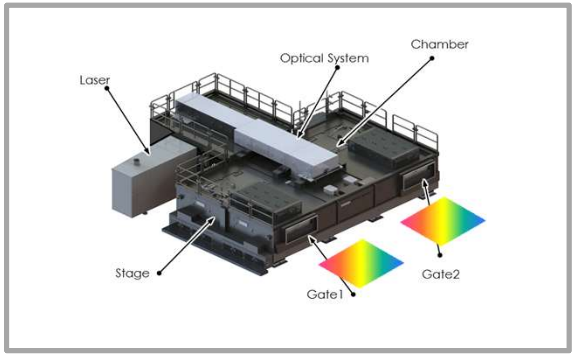
PI
Carrier Glass

TFE
TFT & OLED
PI
Carrier Glass

TFE
TFT & OLED
PI
Laser Lift-Off
Carrier Glass

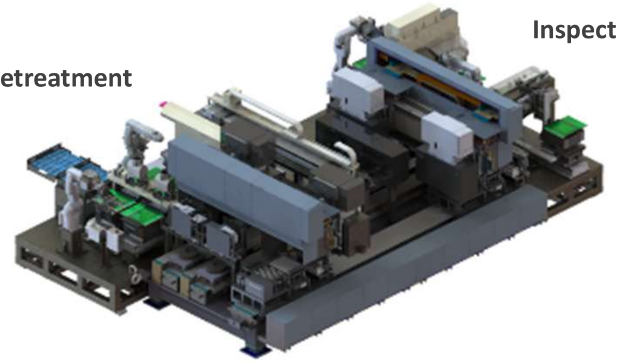
Laser beam





New Equipment

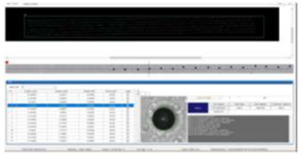
Module OCR IJP(Inkjet Printer)



[Inkjet System]

Advantage of APS’ IJP

- High Performance Printing
- Easy User Interface
- Inspection : 2D , 3D , AOI
- Compact Equipment
- Best Maintenance



Technology

IJP Process

Jetting Condition

Wave form tuning

High Uniformity

Ink Printing

UV Curing

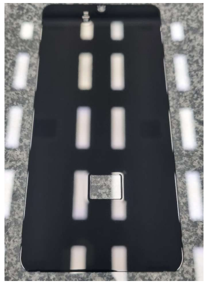
Inspection

Result

OCA (Optically Clear Adhesive)

OCR (Optically Clear Resin)

[Coating Image]

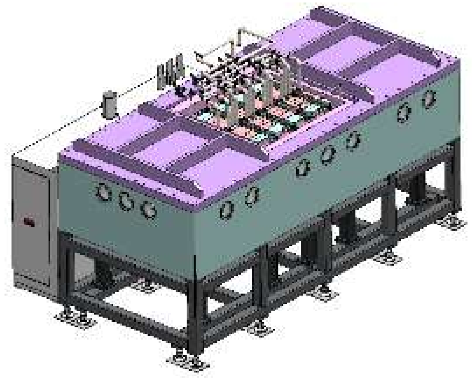


- Thickness : 150 ~200um

New Equipment

AP Systems

PEALD (Plasma Enhanced Atomic Layer Deposition) : M-type For 8.5G IT OLED



[M-ALD : Glass Moving]

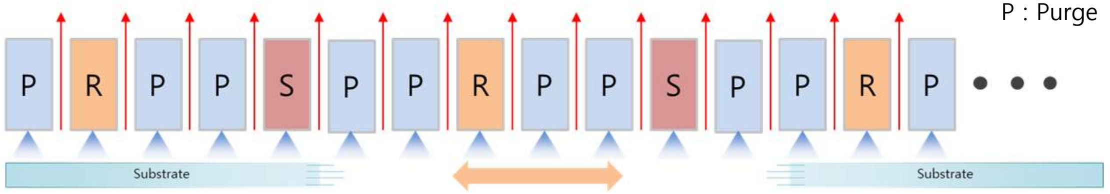
Space Divided ALD for Oxide TFT(IGZO)

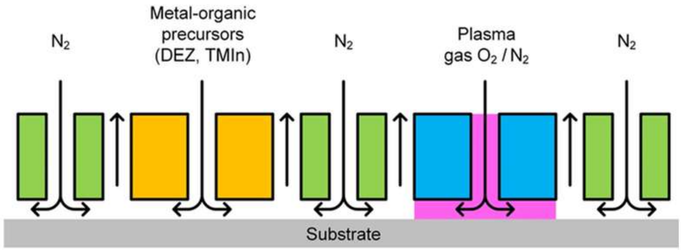
- **High deposition rate than Conventional ALD**
  - **→ Dep. Rate > 40Å/min**
- **Spatial separation of reaction, instead of time one**
  - **→ No intermixing of precursor and reactant**

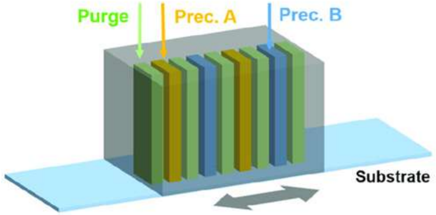
Technology

Rapid Deposition with Multiple linear nozzle & Glass moving

S : Source
R : Reactant
P : Purge

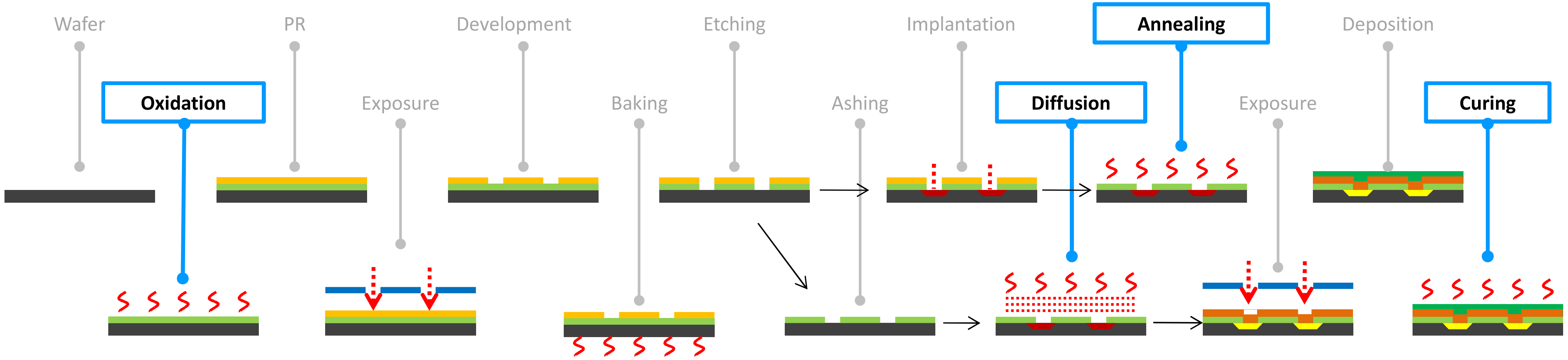


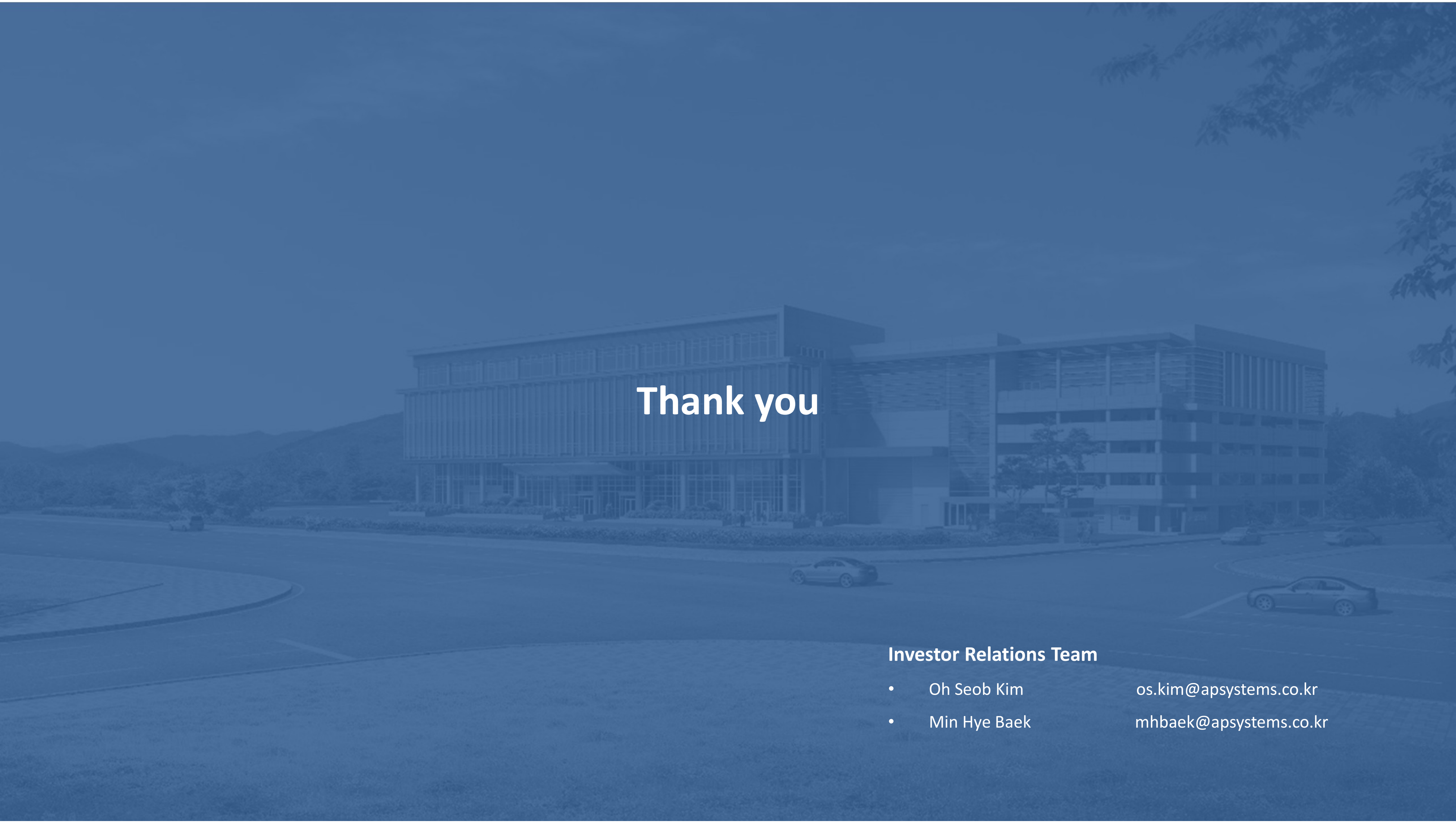




Signature Equipment

RTP (Rapid Thermal Process)





Thank you

Investor Relations Team

Oh Seob Kim	os.kim@apsystems.co.kr
Min Hye Baek	mhbaek@apsystems.co.kr